

## CABLE CONSTRUCTION

1. Fluoropolymer Jacket (Olive Drab)
2. Round Silver-Plated Copper
3. Aluminum Polyimide
4. Silver-Plated Copper Flat Strip Braid
5. PTFE Dielectric
6. Solid Silver-Plated Copper

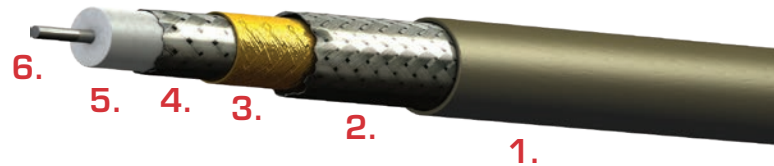
Designed specifically to serve High Frequency Applications on the Ku band & X band, this new Microwave Cable features minimum 200°C on all materials, Silver-Plated Copper throughout, plus: Inner Flat Strip Braid; High Temp Polyimide Foil; and Braided Shield.

Special tooling and specialized technicians ensure your custom cable assembly is done to precision—maximizing the performance of the PIC HT77210F with: Certified Test Process & Equipment-- ISO 9001/AS 9100; Phase-matched Ship Sets; Complete Lot Traceability; Certified Test Reports; and Improved Supply Chain Efficiency. [For quality assurance this cable is sold in an assembly only].

## CONNECTOR DATA

PIC P/N	CONNECTOR TYPE
120508	TNC Straight Plug
120509	TNC 90 Degree Plug
120521	TNC Bulkhead Jack
120510	N Straight Plug
120511	N 90 Degree Plug
120522	N Bulkhead Jack
120514	SMA Straight Plug
120515	SMA 90 Degree Plug
120534	BMB Jack Snap Mount
120535	BMB SZ 5 Jack

**Call PIC For Other Connector Availability**



## PHYSICAL DATA

- Conductor 16 AWG Solid Silver-Plated Copper
- Operating Temperature -55° to +200°C
- Outer Diameter: in (mm) 0.21 (5.28)
- Minimum Bend Radius: in (mm) 1.0 (25.4)
- Weight: lbs/100 ft (kg/100 m) 4.5 (6.7)
- Complies with RoHS (Directive 2002/95/EC)
- Complies with FAR Part 23 and 25, Appendix F

## ELECTRICAL DATA

- Impedance: ohms 50
- Capacitance: pF/ft (m) 26.5 (87.0)
- Velocity of Propagation: % 76.5
- VSWR (Gated) Max 1.20:1
- RF Shielding Effectiveness: dB/min -90
- Attenuation: Nom / Max dB/100 ft (dB/100 m)
  - @1 GHz 7.6 / 8.4 (24.9 / 27.6)
  - @3 GHz 13.7 / 15.1 (44.9 / 49.5)
  - @6 GHz 20.0 / 22.0 (65.6 / 72.2)
  - @12 GHz 29.5 / 32.5 (96.8 / 106.6)
  - @18 GHz 37.3 / 40.1 (122.4 / 131.6)
  - @26 GHz 46.2 / 50.9 (151.6 / 167.0)
- K Values (nom loss): K1 = 0.232, K2 = 0.00034
- Formula for Attenuation:  $(K1 * \sqrt{F(MHz)}) + (K2 * F(MHz))$

*All values nominal unless otherwise noted*

**2 WEEK LEAD TIME OR LESS ON MOST ASSEMBLIES**